

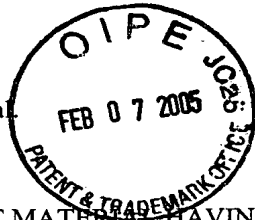
Docket No. 213480US0

IN RE APPLICATION OF: Sei TSUNODA, et al.

SERIAL NO: 09/942,626

FILED: August 31, 2001

FOR: LOW DIELECTRIC CONSTANT MATERIAL HAVING THERMAL RESISTANCE, INSULATION FILM BETWEEN SEMICONDUCTOR LAYERS USING THE SAME, AND SEMICONDUCTOR DEVICE



RESPONSE UNDER 37 CFR 1.116-
EXPEDITED PROCEDURE EXAMINING
GROUP 1751

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

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SIR:

Transmitted herewith is an amendment in the above-identified application.

- ☒ No additional fee is required
- ☐ Small entity status of this application under 37 C.F.R. §1.9 and §1.27 is claimed.
- ☐ Additional documents filed herewith:

The Fee has been calculated as shown below:

CLAIMS	CLAIMS REMAINING		HIGHEST NUMBER PREVIOUSLY PAID	NO. EXTRA CLAIMS	RATE	CALCULATIONS
TOTAL	8	MINUS	20	0	x \$50 =	\$0.00
INDEPENDENT	5	MINUS	6	0	x \$200 =	\$0.00
		<input type="checkbox"/> MULTIPLE DEPENDENT CLAIMS			+ \$360 =	\$0.00
		TOTAL OF ABOVE CALCULATIONS				\$0.00
		<input type="checkbox"/> Reduction by 50% for filing by Small Entity				\$0.00
		<input type="checkbox"/> Recordation of Assignment			+ \$40 =	\$0.00
		TOTAL				\$0.00

- ☐ A check in the amount of **\$0.00** is attached.
- ☐ Credit card payment form is attached to cover the fees in the amount of **\$0.00**
- ☒ Please charge any additional Fees for the papers being filed herewith and for which no check or credit card payment is enclosed herewith, or credit any overpayment to deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.
- ☒ If these papers are not considered timely filed by the Patent and Trademark Office, then a petition is hereby made under 37 C.F.R. §1.136, and any additional fees required under 37 C.F.R. §1.136 for any necessary extension of time may be charged to Deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.

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"RESPONSE UNDER 37 CFR 1.116-
EXPEDITED PROCEDURE EXAMINING
GROUP 1751"

DOCKET NO: 213480US0

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF :
SEI TSUNODA, ET AL. : EXAMINER: HAMLIN, D. G.
SERIAL NO: 09/942,626 :
FILED: AUGUST 31, 2001 : GROUP ART UNIT: 1751
FOR: LOW DIELECTRIC CONSTANT :
MATERIAL HAVING THERMAL
RESISTANCE, INSULATION FILM
BETWEEN SEMICONDUCTOR LAYERS
USING THE SAME, AND
SEMICONDUCTOR DEVICE

AMENDMENT UNDER 37 CFR 1.116

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

SIR:

Responsive to the Final Office Action dated November 19, 2004, Applicants respectfully request reconsideration of the above-identified application **and the finality of the Office Action**, in view of the following amendment and remarks.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Discussion of the Amendment begins on page 7 of this paper.

Remarks begin on page 8 of this paper.